

In the Claims:

1-10. (Cancelled).

11. (Previously Presented) Circuit board, comprising:
~~at least one rigid area;~~
~~at least one flexible area;~~
a rigid individual layer which is provided with printed conductors or is copper-clad on at least one side, said rigid individual layer having at least one rigid area and at least one flexible area,
at least one copper foil,
an adhesive medium directly connecting the at least one copper foil to the rigid individual layer, and
~~at least one copper foil;~~
wherein ~~the rigid area~~ there being is no flexible individual layer between the adhesive medium and the at least one copper foil in the rigid area of the rigid individual layer, and the flexible area, an insulating layer being is affixed applied directly to an inner side of the copper foil in the at least one flexible area of the rigid individual layer,
wherein the adhesive medium has recesses in an opening in alignment with the flexible area of the rigid individual layer,
wherein, in the flexible area of the rigid individual layer, there is no flexible individual layer between the rigid individual layer and the copper foil, and
wherein the insulating layer is a resist applied to the copper foil.

12. (Previously Presented) Circuit board as claimed in claim 11, wherein the resist is a flexible solder resist.

13. (Currently Amended) Circuit board as claimed in claim 11, wherein, at least in the flexible area, another insulating layer is applied to the outer side of the copper foil.

14. (Previously Presented) Circuit board as claimed in claim 13, the other insulating layer is a resist which has been applied to the copper foil.

15. (Cancelled).

16. (Withdrawn) Process for producing rigid-flexible circuit boards with at least one rigid individual layer which is provided with printed conductors or is copper-clad on at least one side, with an adhesive medium and with at least one copper foil, the adhesive medium having recesses in the flexible area, comprising the steps of:

first, applying an uncured insulating layer to one side of the copper foil in the flexible area,

curing the insulating layer to such an extent that a free surface loses its adhesive capacity,

following the preceding steps, cementing the copper foil by means of the adhesive medium to the rigid individual layer and

then moving a piece from the rigid individual layer in the flexible area of the circuit board.

17. (Withdrawn) Process as claimed in claim 16, wherein at least in the flexible area of the circuit board another insulating layer is applied to the outer side of the copper foil.

18. (Withdrawn) Process as claimed in claim 17, wherein the insulating layers are applied to the copper foil by one of spraying, rolling or printing.

19. (Withdrawn) Process as claimed in claim 16, wherein the insulating layer is applied to the copper foil by one of spraying, rolling or printing.